

Smart Power High-Side-Switch

Features

- Overload protection
- Current limitation
- Short circuit protection
- Thermal shutdown with restart
- Overvoltage protection (including load dump)
- Fast demagnetization of inductive loads
- Reverse battery protection with external resistor
- CMOS compatible input
- Loss of GND and loss of V_{bb} protection
- ESD - Protection
- Very low standby current

Product Summary

Overvoltage protection	$V_{bb(AZ)}$	41	V
Operating voltage	$V_{bb(on)}$	5...34	V
On-state resistance	R_{ON}	60	m Ω
Nominal load current	$I_{L(nom)}$	2.6	A



P-DSO-8

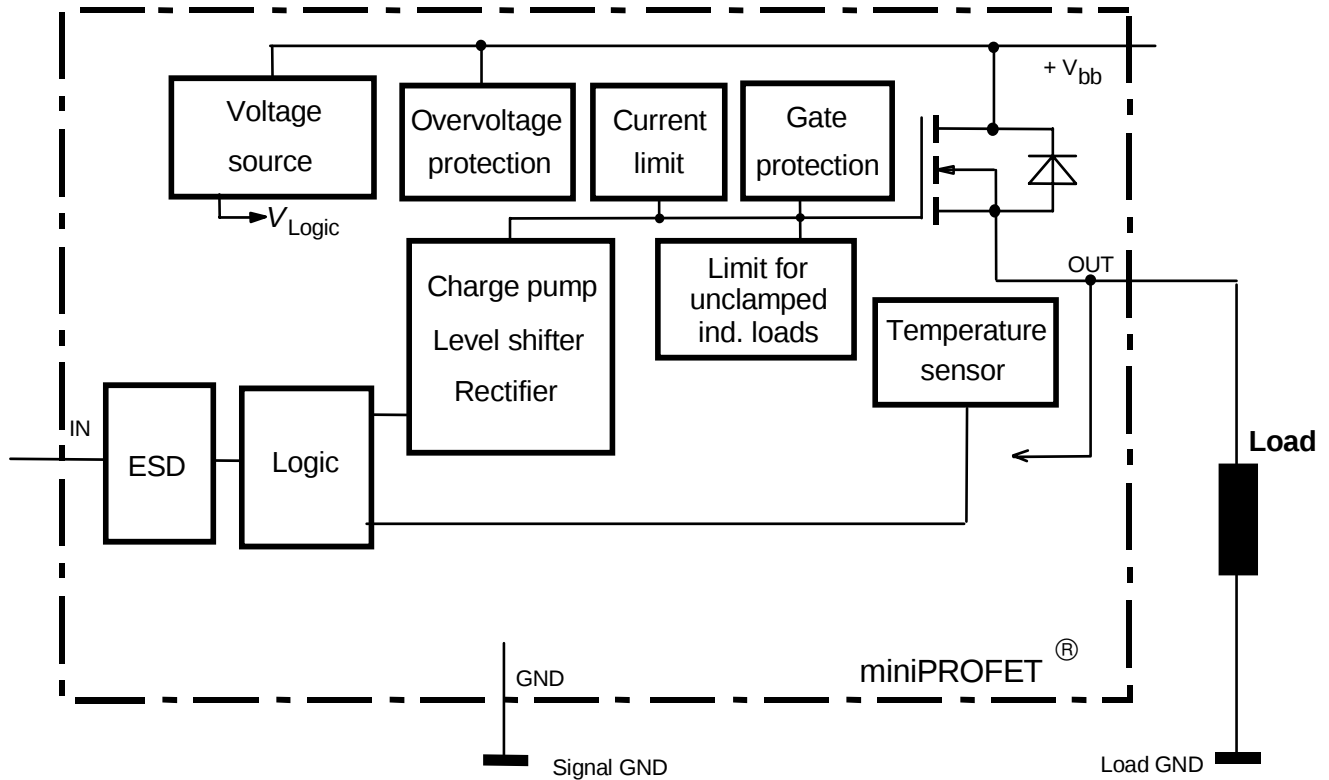
Application

- All types of resistive, inductive and capacitive loads
- μ C compatible power switch for 12 V and 24 V DC applications
- Replaces electromechanical relays and discrete circuits

General Description

N channel vertical power FET with charge pump, ground referenced CMOS compatible input, monolithically integrated in Smart SIPMOS[®] technology. Fully protected by embedded protection functions.

Block Diagram



Pin	Symbol	Function
1	GND	Logic ground
2	IN	Input, activates the power switch in case of logic high signal
3	OUT	Output to the load
4	NC	not connected
5	Vbb	Positive power supply voltage
6	Vbb	Positive power supply voltage
7	Vbb	Positive power supply voltage
8	Vbb	Positive power supply voltage

Maximum Ratings at $T_j=25^{\circ}\text{C}$, unless otherwise specified

Parameter	Symbol	Value	Unit
Supply voltage	V_{bb}	40	V
Supply voltage for full short circuit protection $T_j = -40...+150^{\circ}\text{C}$	$V_{bb(SC)}$	36	
Continuous input voltage	V_{IN}	-10 ... +16	
Load current (Short - circuit current, see page 5)	I_L	self limited	A
Current through input pin (DC)	I_{IN}	± 5	μA
Operating temperature	T_j	-40 ... +150	$^{\circ}\text{C}$
Storage temperature	T_{stg}	-55 ... +150	
Power dissipation ¹⁾	P_{tot}	1.5	W
Inductive load switch-off energy dissipation ¹⁾²⁾ single pulse, (see page 8) $T_j = 150^{\circ}\text{C}$, $V_{bb} = 13.5\text{ V}$, $I_L = 1.5\text{ A}$	E_{AS}	900	mJ
Load dump protection ²⁾ $V_{LoadDump}^{3)} = V_A + V_S$ $R_I = 2\Omega$, $t_d = 400\text{ms}$, $V_{IN} = \text{low or high}$, $V_A = 13.5\text{V}$ $R_L = 9\Omega$	$V_{Loaddump}$	63	V
Electrostatic discharge voltage (Human Body Model) according to MIL STD 883D, method 3015.7 and EOS/ESD assn. standard S5.1 - 1993 Input pin all other pins	V_{ESD}	± 1 ± 5	kV

Thermal Characteristics

Thermal resistance @ min. footprint	$R_{th(JA)}$	-	95	-	K/W
Thermal resistance @ 6 cm ² cooling area ¹⁾	$R_{th(JA)}$	-	70	83	

¹⁾ Device on 50mm*50mm*1.5mm epoxy PCB FR4 with 6 cm² (one layer, 70 μm thick) copper area for drain connection. PCB is vertical without blown air. (see page 16)

²⁾ not tested, specified by design

³⁾ $V_{Loaddump}$ is setup without the DUT connected to the generator per ISO 7637-1 and DIN 40839 .

Supply voltages higher than $V_{bb(AZ)}$ require an external current limit for the GND pin, e.g. with a 150 Ω resistor in GND connection. A resistor for the protection of the input is integrated.

Electrical Characteristics

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

at $T_j = -40...+150^{\circ}\text{C}$, $V_{bb}=13.5\text{V}$, unless otherwise specified

Load Switching Capabilities and Characteristics

On-state resistance $T_j = 25^{\circ}\text{C}$, $I_L = 2\text{ A}$ $T_j = 150^{\circ}\text{C}$	R_{ON}	-	50 95	60 120	mΩ
Nominal load current; Device on PCB ¹⁾ $T_C = 85^{\circ}\text{C}$, $T_j \leq 150^{\circ}\text{C}$	$I_{L(nom)}$	2.6	3.1	-	A
Turn-on time to 90% V_{OUT} $R_L = 47\ \Omega$	t_{on}	-	90	180	μs
Turn-off time to 10% V_{OUT} $R_L = 47\ \Omega$	t_{off}	-	110	230	
Slew rate on 10 to 30% V_{OUT} , $R_L = 47\ \Omega$	dV/dt_{on}	-	0.7	1.5	V/μs
Slew rate off 70 to 40% V_{OUT} , $R_L = 47\ \Omega$	$-dV/dt_{off}$	-	0.7	1.5	

Operating Parameters

Operating voltage	$V_{bb(on)}$	5	-	34	V
Undervoltage shutdown of charge pump $T_j = -40...+85^{\circ}\text{C}$ $T_j = 150^{\circ}\text{C}$	$V_{bb(under)}$	- -	- -	4 5.5	
Undervoltage restart of charge pump	$V_{bb(u\ cp)}$	-	4	5.5	V
Standby current $V_{IN} = 0\text{ V}$, $T_j = -40 \dots +85^{\circ}\text{C}$ $V_{IN} = 0\text{ V}$, $T_j = 150^{\circ}\text{C}$ ²⁾	$I_{bb(off)}$	- -	- -	10 15	μA
Leakage output current (included in $I_{bb(off)}$) $V_{IN} = 0\text{ V}$	$I_{L(off)}$	-	-	5	
Operating current $V_{IN} = 5\text{ V}$	I_{GND}	-	0.8	1.5	mA

¹ Device on 50mm*50mm*1.5mm epoxy PCB FR4 with 6 cm² (one layer, 70μm thick) copper area for drain connection. PCB is vertical without blown air. (see page 16)

² higher current due temperature sensor

Electrical Characteristics

Parameter and Conditions at $T_j = -40...+150^\circ\text{C}$, $V_{bb}=13.5\text{V}$, unless otherwise specified	Symbol	Values			Unit
		min.	typ.	max.	

Protection Functions

Initial peak short circuit current limit (pin 5 to 3) $T_j = -40^\circ\text{C}$, $V_{bb} = 20\text{V}$, $t_m = 150\text{ }\mu\text{s}$ $T_j = 25^\circ\text{C}$ $T_j = 150^\circ\text{C}$	$I_{L(SCp)}$	- - 9	- 17 -	28 - -	A
Repetitive short circuit current limit $T_j = T_{jt}$ (see timing diagrams)	$I_{L(SCr)}$	-	12	-	
Output clamp (inductive load switch off) at $V_{OUT} = V_{bb} - V_{ON(CL)}$, $I_{bb} = 4\text{ mA}$	$V_{ON(CL)}$	41	47	-	V
Overvoltage protection ¹⁾ $I_{bb} = 4\text{ mA}$	$V_{bb(AZ)}$	41	-	-	
Thermal overload trip temperature	T_{jt}	150	-	-	$^\circ\text{C}$
Thermal hysteresis	ΔT_{jt}	-	10	-	K

Reverse Battery

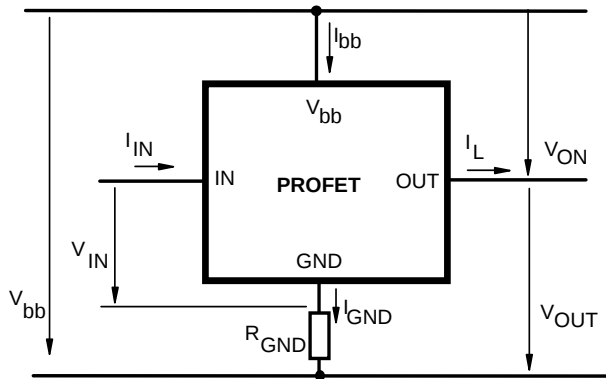
Reverse battery ²⁾	$-V_{bb}$	-	-	32	V
Drain-source diode voltage ($V_{OUT} > V_{bb}$) $T_j = 150^\circ\text{C}$	$-V_{ON}$	-	600	-	mV

¹see also $V_{ON(CL)}$ in circuit diagram on page 7

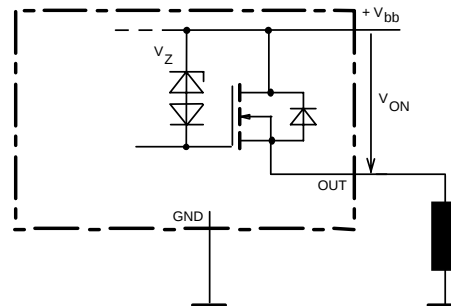
²Requires a $150\text{ }\Omega$ resistor in GND connection. The reverse load current through the intrinsic drain-source diode has to be limited by the connected load. Power dissipation is higher compared to normal operating conditions due to the voltage drop across the drain-source diode. The temperature protection is not active during reverse current operation! Input current has to be limited (see max. ratings page 3).

Parameter and Conditions at $T_j = -40...+150^{\circ}\text{C}$, $V_{bb}=13.5\text{V}$, unless otherwise specified	Symbol	Values			Unit
		min.	typ.	max.	
Input					
Input turn-on threshold voltage (see page 12)	$V_{\text{IN(T+)}}$	-	-	2.2	V
Input turn-off threshold voltage (see page 12)	$V_{\text{IN(T-)}}$	0.8	-	-	
Input threshold hysteresis	$\Delta V_{\text{IN(T)}}$	-	0.3	-	V
Off state input current (see page 12) $V_{\text{IN}} = 0.7 \text{ V}$	$I_{\text{IN(off)}}$	1	-	25	μA
On state input current (see page 12) $V_{\text{IN}} = 5 \text{ V}$	$I_{\text{IN(on)}}$	3	-	25	
Input resistance (see page 7)	R_i	1.5	3.5	5	$\text{k}\Omega$

Terms

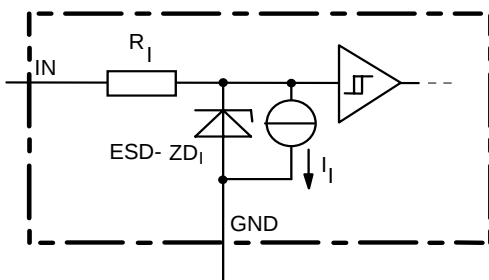


Inductive and overvoltage output clamp



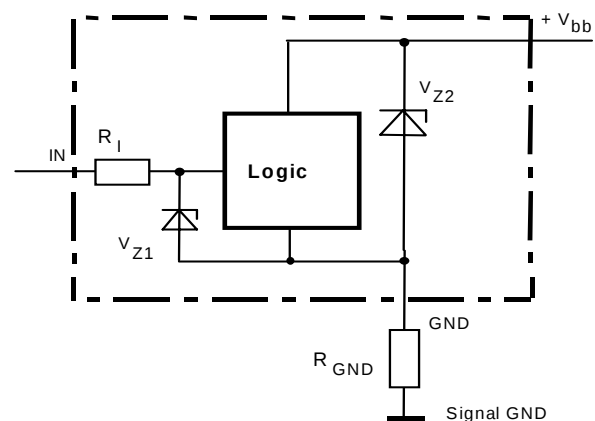
V_{ON} clamped to 47 V typ.

Input circuit (ESD protection)



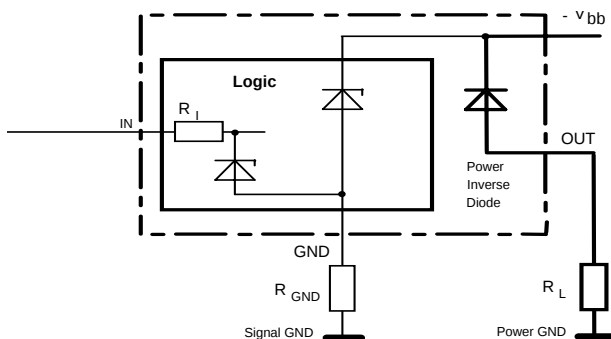
The use of ESD zener diodes as voltage clamp at DC conditions is not recommended

Overvoltage protection of logic part



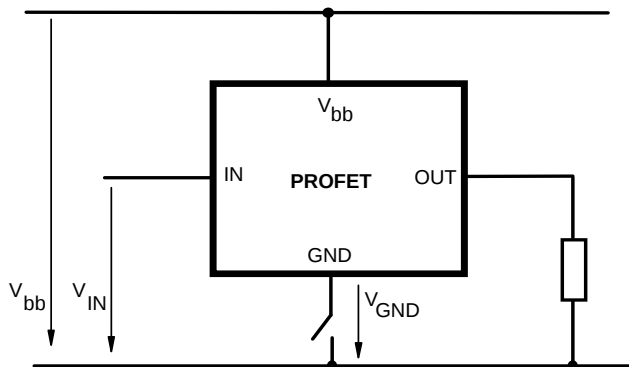
$V_{Z1}=6.1V$ typ., $V_{Z2}=V_{bb(AZ)}=47V$ typ.,
 $R_I=3.5\text{ k}\Omega$ typ., $R_{GND}=150\Omega$

Reverse battery protection

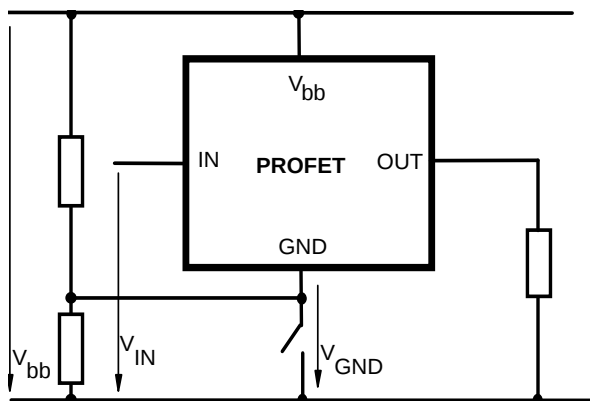


$R_{GND}=150\Omega$, $R_I=3.5\text{ k}\Omega$ typ.,
 Temperature protection is not active during inverse current

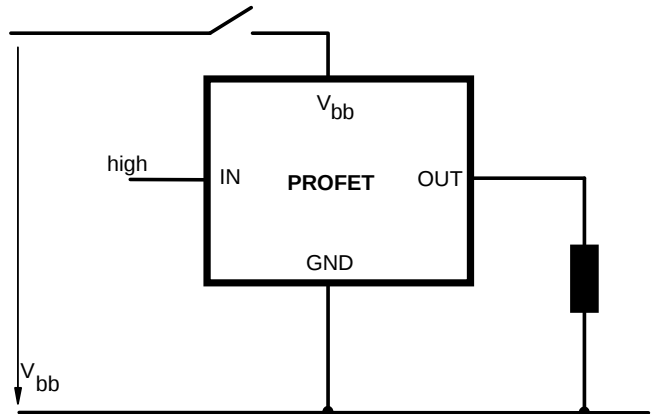
GND disconnect



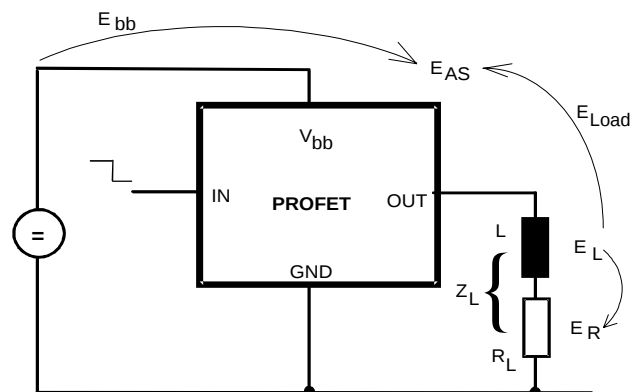
GND disconnect with GND pull up



V_{bb} disconnect with charged inductive load



Inductive Load switch-off energy dissipation



Energy stored in load inductance: $E_L = \frac{1}{2} * L * I_L^2$

While demagnetizing load inductance,

the energy dissipated in PROFET is

$$E_{AS} = E_{bb} + E_L - E_R = \int V_{ON(CL)} * i_L(t) dt,$$

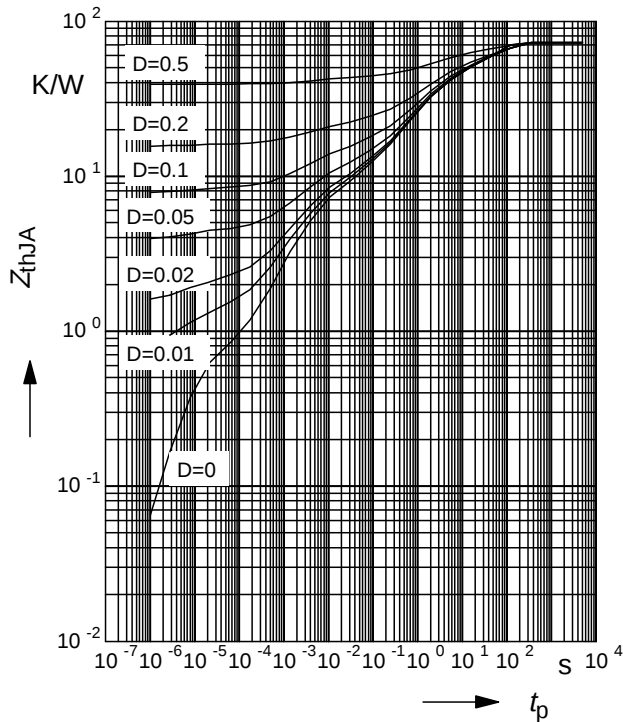
with an approximate solution for $R_L > 0\Omega$:

$$E_{AS} = \frac{I_L * L}{2 * R_L} * (V_{bb} + |V_{OUT(CL)}|) * \ln(1 + \frac{I_L * R_L}{|V_{OUT(CL)}|})$$

Typ. transient thermal impedance

$Z_{thJA}=f(t_p)$ @ 6cm² heatsink area

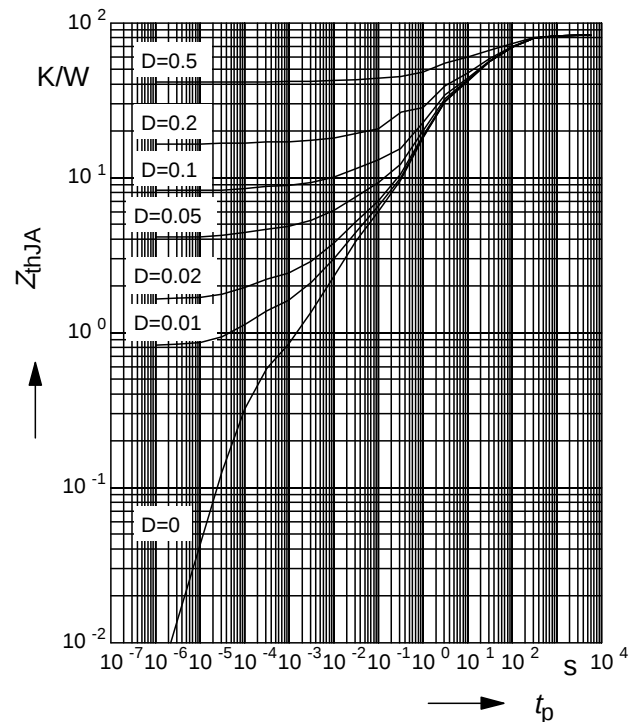
Parameter: $D=t_p/T$



Typ. transient thermal impedance

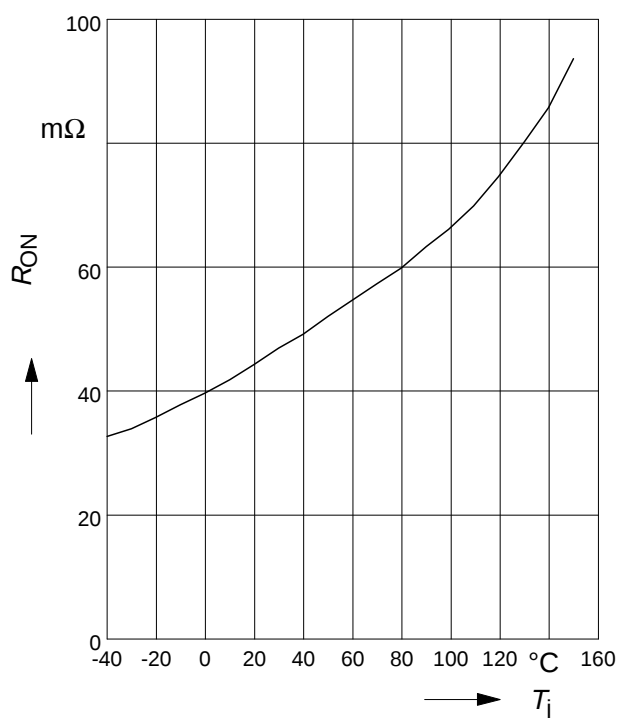
$Z_{thJA}=f(t_p)$ @ min. footprint

Parameter: $D=t_p/T$



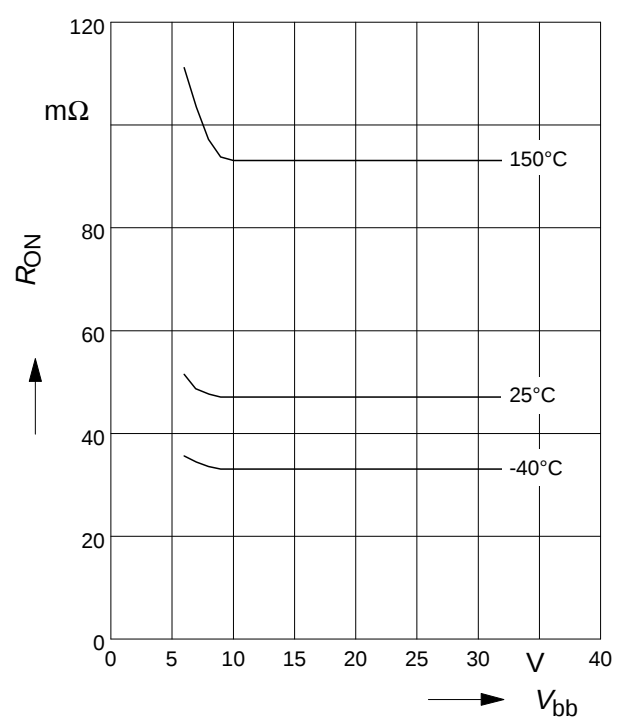
Typ. on-state resistance

$R_{ON} = f(T_j)$; $V_{bb} = 13,5V$; $V_{in} = \text{high}$



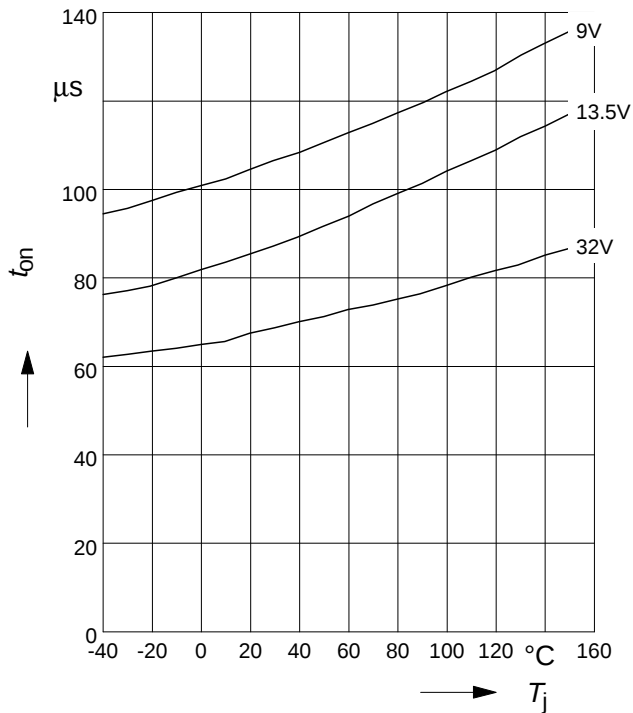
Typ. on-state resistance

$R_{ON} = f(V_{bb})$; $I_L = 0.5A$; $V_{in} = \text{high}$



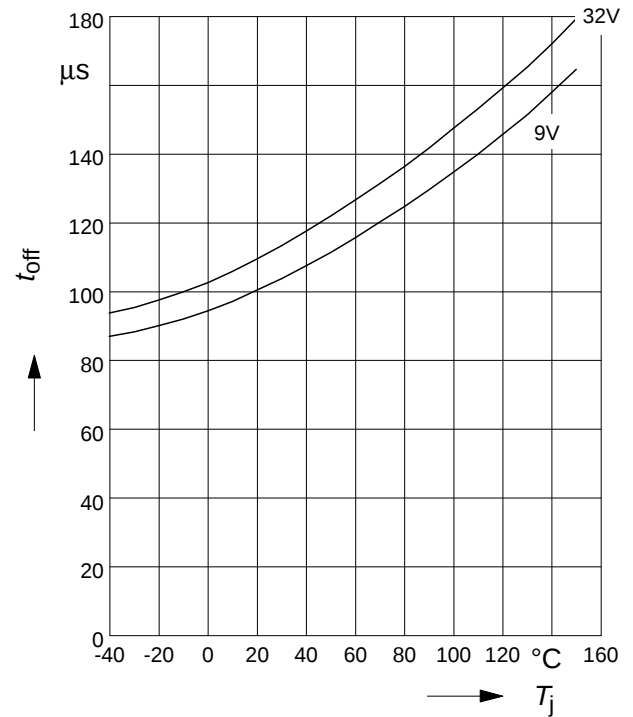
Typ. turn on time

$$t_{on} = f(T_j); R_L = 47\Omega$$



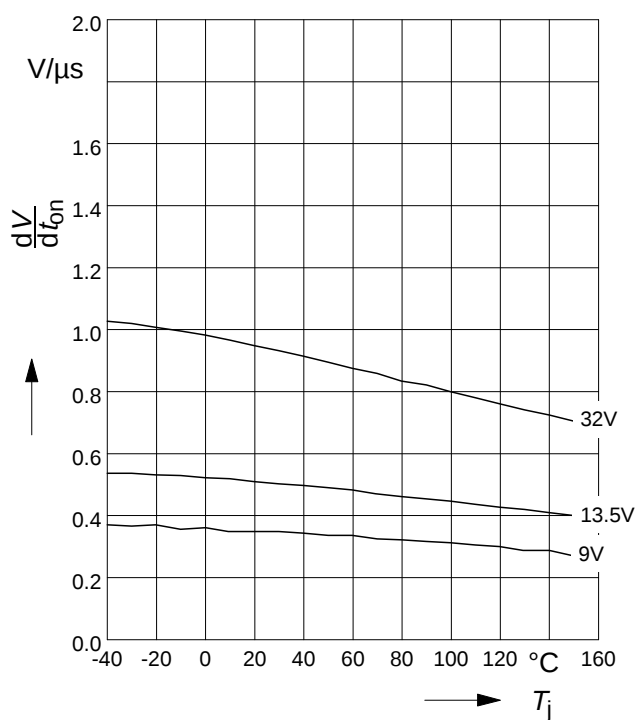
Typ. turn off time

$$t_{off} = f(T_j); R_L = 47\Omega$$



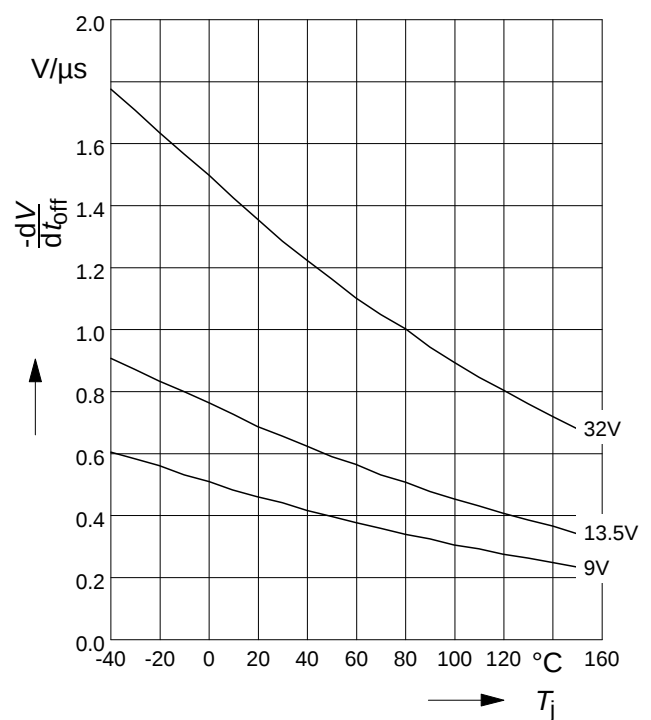
Typ. slew rate on

$$dV/dt_{on} = f(T_j); R_L = 47\Omega$$



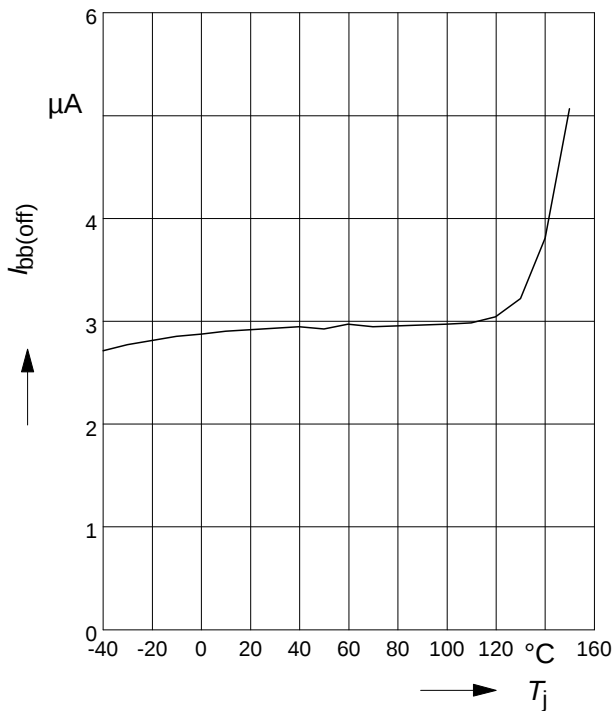
Typ. slew rate off

$$-dV/dt_{off} = f(T_j); R_L = 47\Omega$$



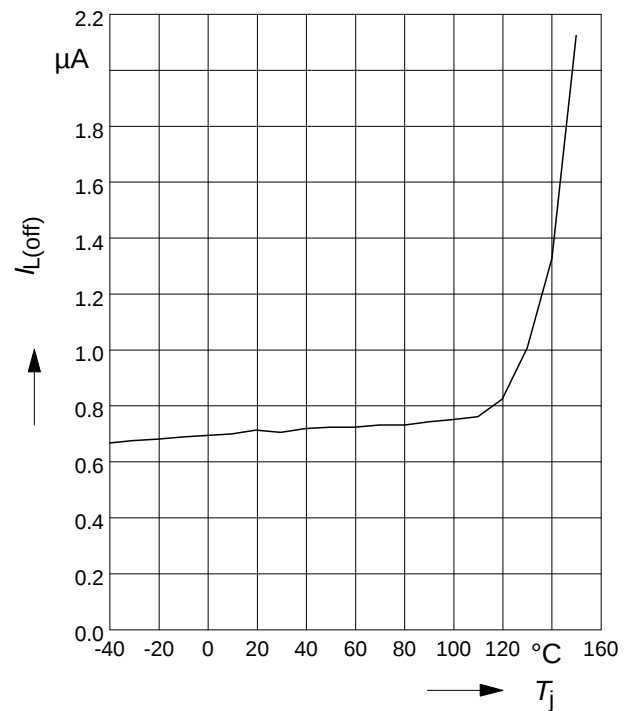
Typ. standby current

$$I_{bb(off)} = f(T_j) ; V_{bb} = 32V ; V_{IN} = low$$



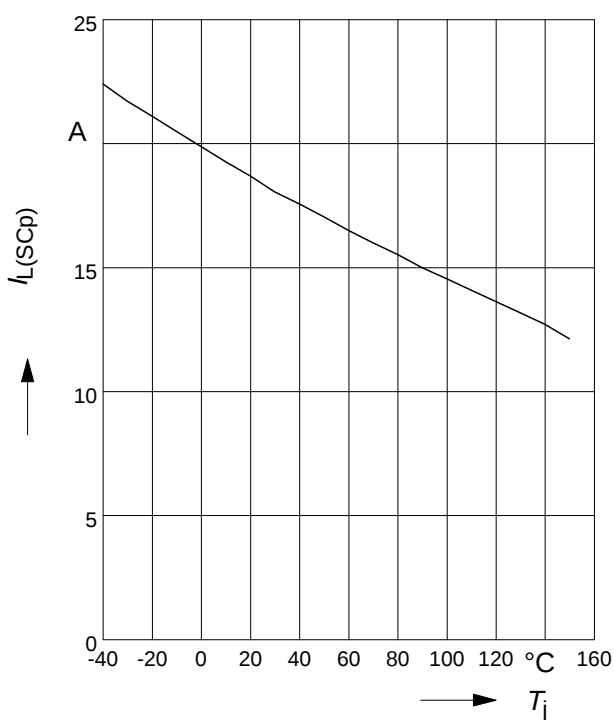
Typ. leakage current

$$I_L(off) = f(T_j) ; V_{bb} = 32V ; V_{IN} = low$$



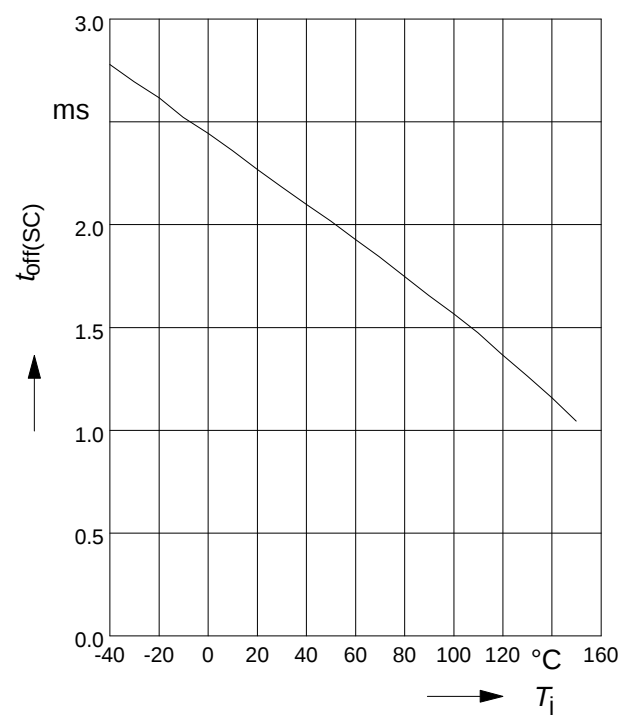
Typ. initial peak short circuit current limit

$$I_{L(SCp)} = f(T_j) ; V_{bb} = 20V$$



Typ. initial short circuit shutdown time

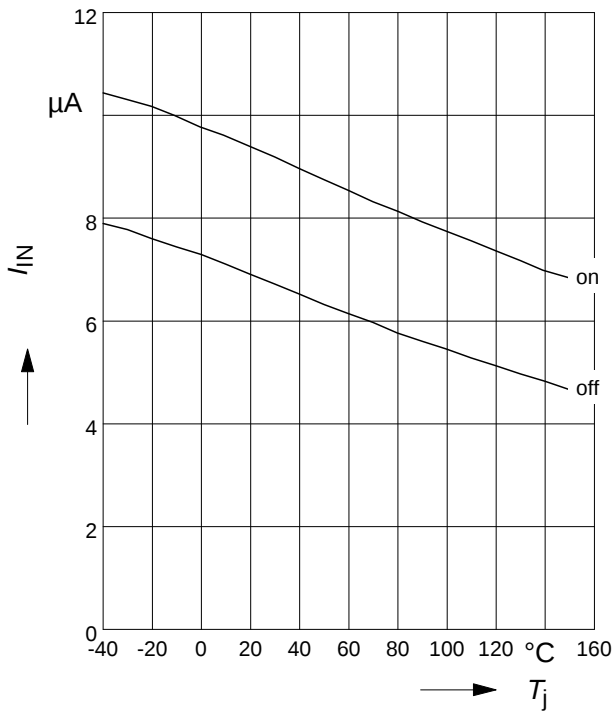
$$t_{off(SC)} = f(T_{j,start}) ; V_{bb} = 20V$$



Typ. input current

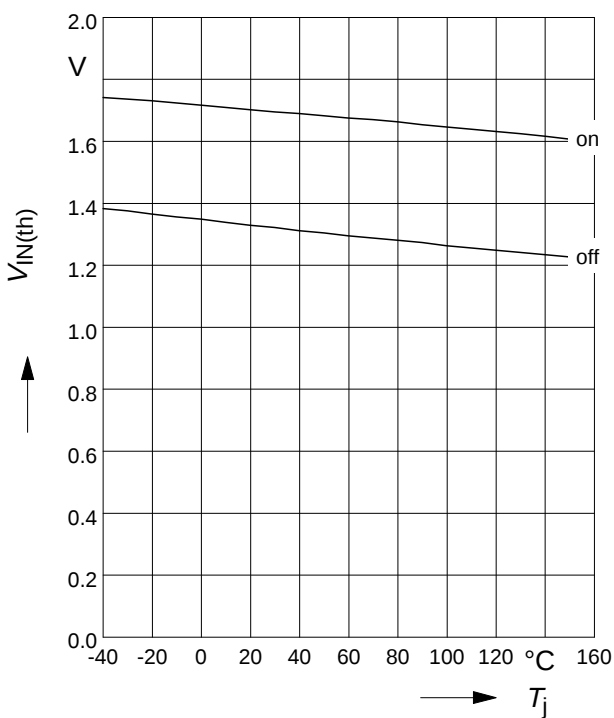
$I_{IN(on/off)} = f(T_j)$; $V_{bb} = 13,5V$; $V_{IN} = \text{low/high}$

$V_{INlow} \leq 0,7V$; $V_{INhigh} = 5V$



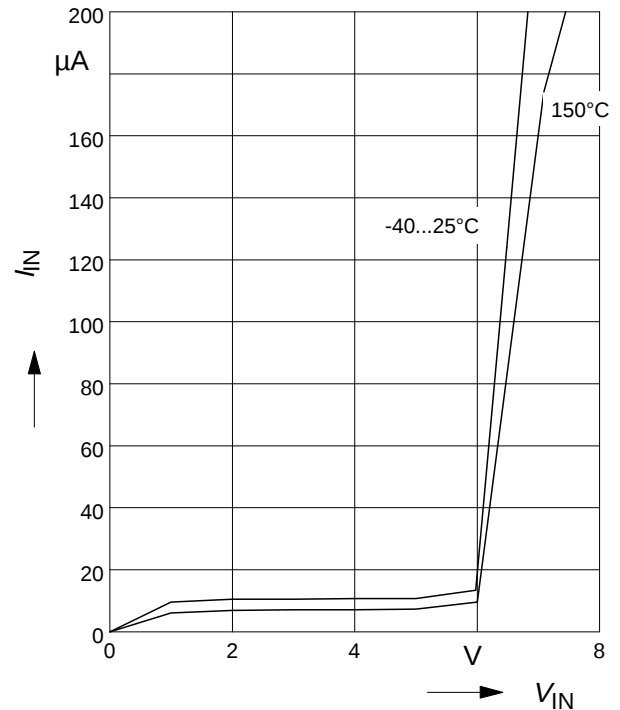
Typ. input threshold voltage

$V_{IN(th)} = f(T_j)$; $V_{bb} = 13,5V$



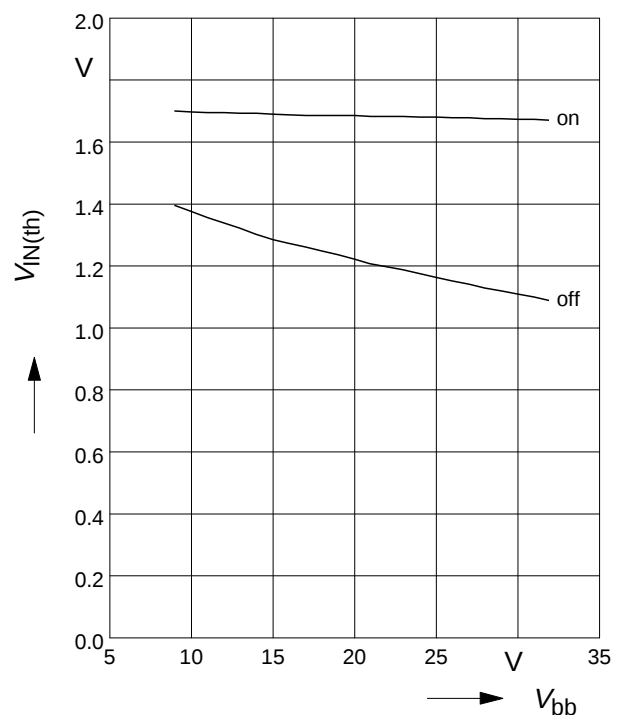
Typ. input current

$I_{IN} = f(V_{IN})$; $V_{bb} = 13.5V$



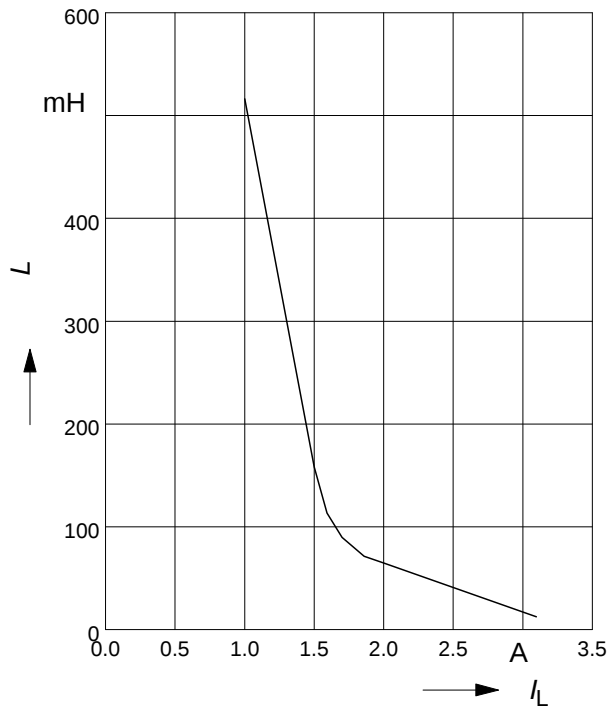
Typ. input threshold voltage

$V_{IN(th)} = f(V_{bb})$; $T_j = 25^\circ C$



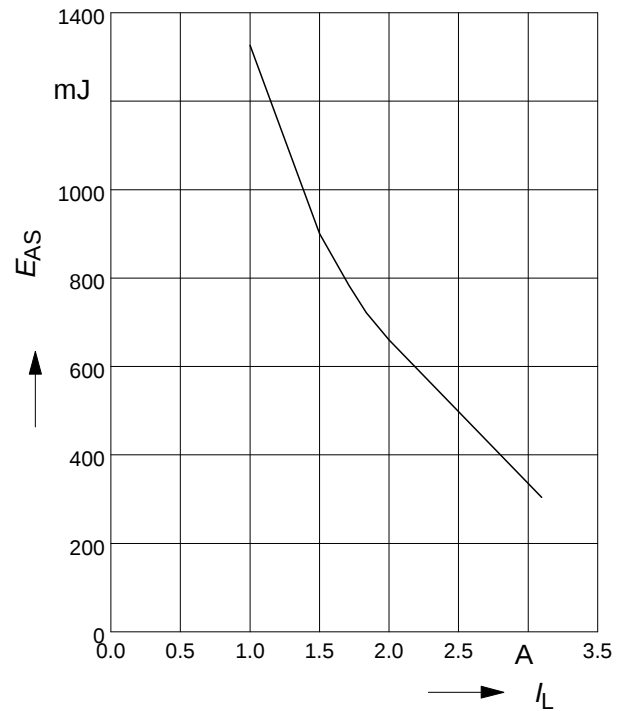
Maximum allowable load inductance for a single switch off

$L = f(I_L)$; $T_{jstart}=150^{\circ}\text{C}$, $V_{bb}=13.5\text{V}$, $R_L=0\Omega$



Maximum allowable inductive switch-off energy, single pulse

$E_{AS} = f(I_L)$; $T_{jstart} = 150^{\circ}\text{C}$, $V_{bb} = 13.5\text{V}$



Timing diagrams

Figure 1a: V_{bb} turn on:

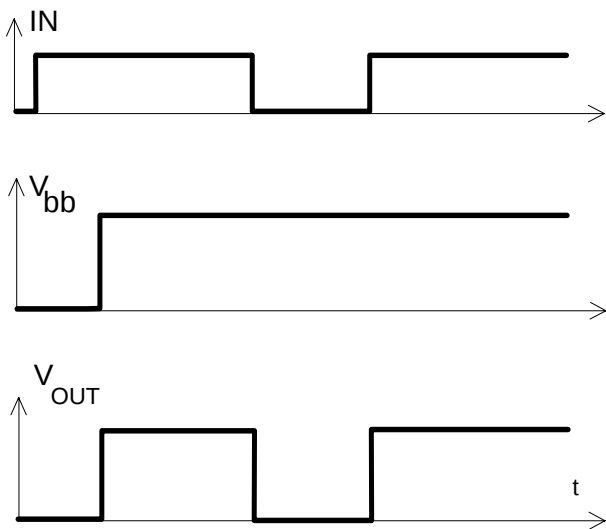


Figure 2b: Switching a lamp,

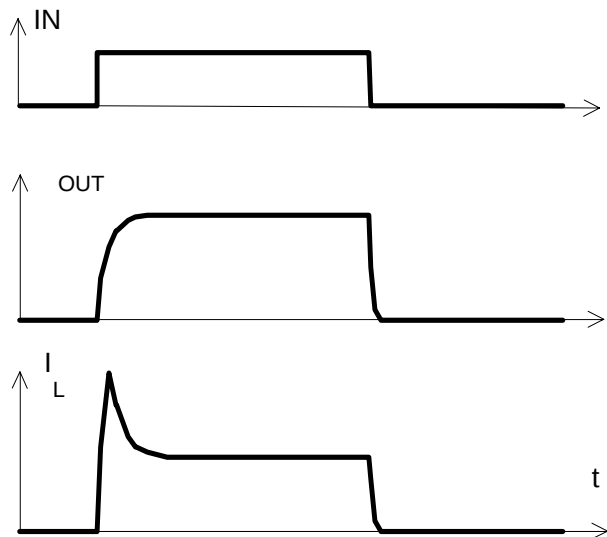


Figure 2a: Switching a resistive load, turn-on/off time and slew rate definition

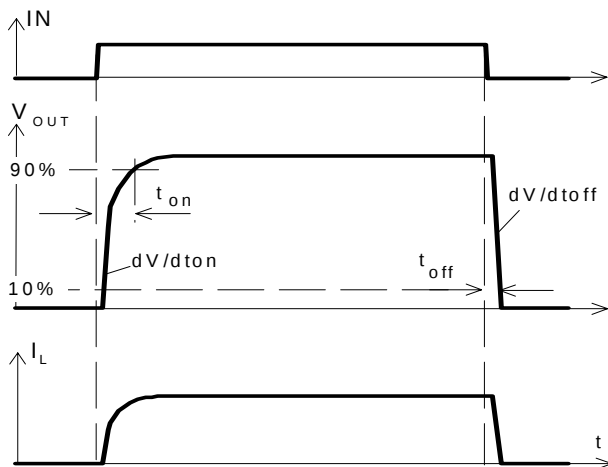


Figure 2c: Switching an inductive load

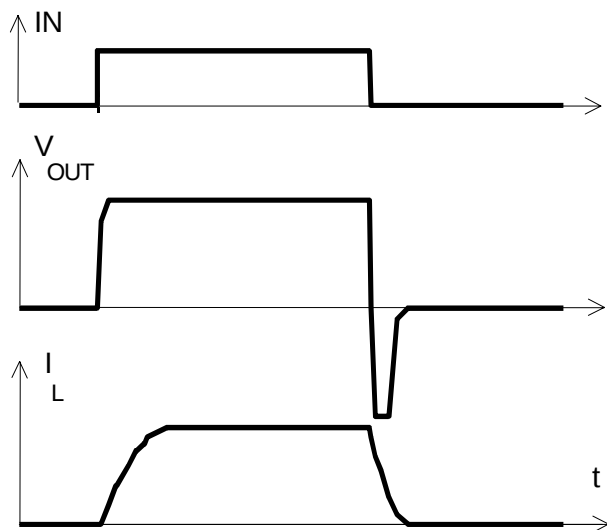
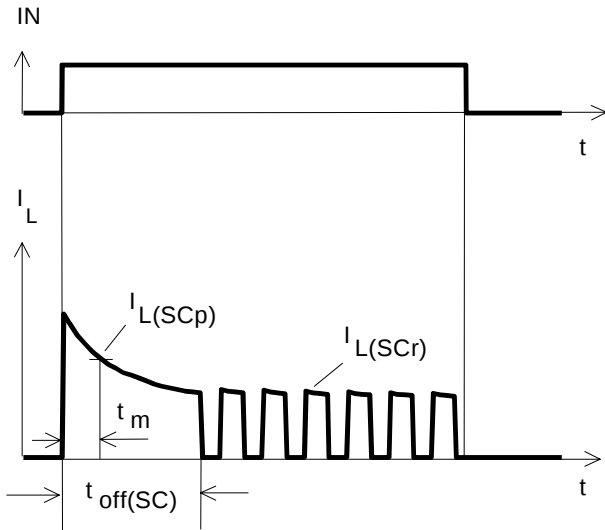


Figure 3a: Turn on into short circuit, shut down by overtemperature, restart by cooling



Heating up of the chip may require several milliseconds, depending on external conditions.

Figure 4: Overtemperature: Reset if $T_j < T_{jt}$

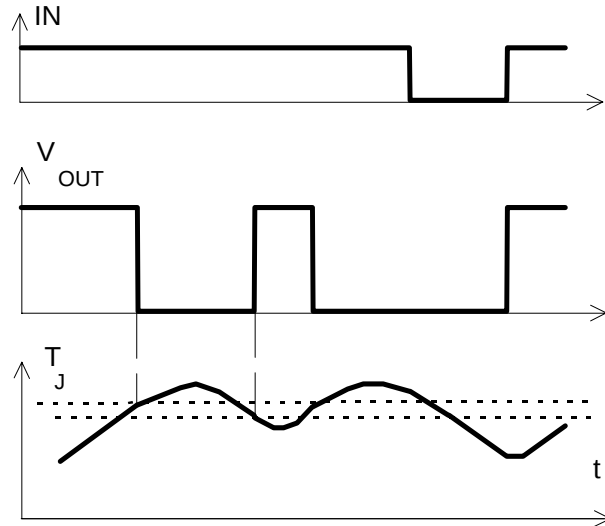
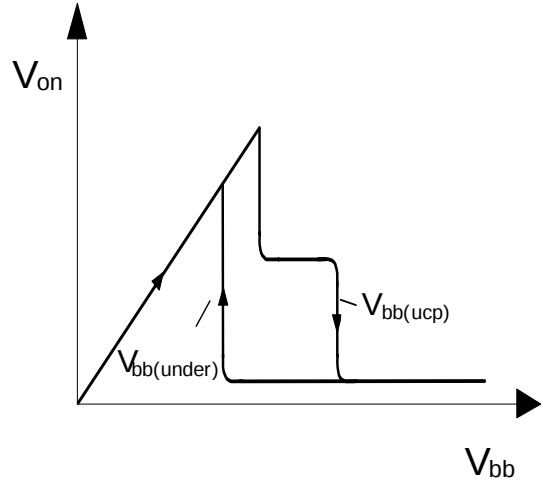


Figure 5: Undervoltage restart of charge pump

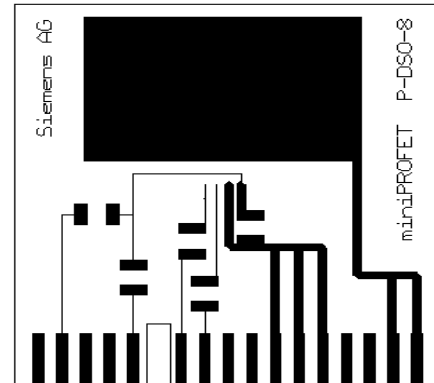
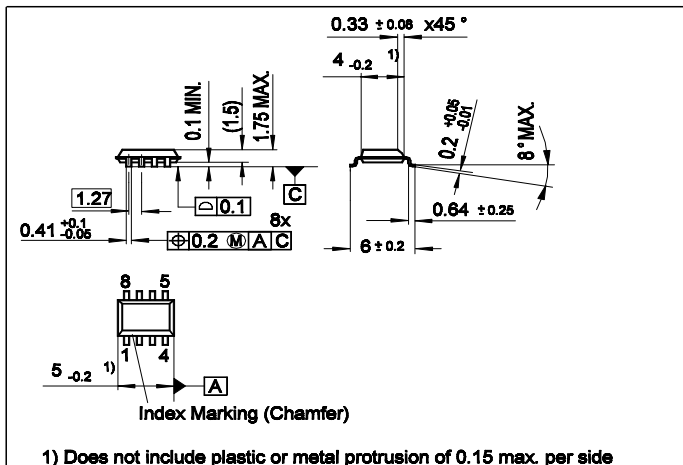


Package and ordering code

all dimensions in mm

Ordering code:

Q67060-S7302-A2



Printed circuit board (FR4, 1.5mm thick, one layer 70µm, 6cm² active heatsink area) as a reference for max. power dissipation P_{tot} nominal load current $I_{L(nom)}$ and thermal resistance R_{thja}

Edition 03 / 1999

Published by Siemens AG,
Bereich Halbleiter Vertrieb,
Werbung, Balanstraße 73,
81541 München

© Siemens AG 1997

All Rights Reserved.

Attention please!

As far as patents or other rights of third parties are concerned, liability is only assumed for components, not for applications, processes and circuits implemented within components or assemblies.

The information describes a type of component and shall not be considered as warranted characteristics.

Terms of delivery and rights to change design reserved.

For questions on technology, delivery and prices please contact the Semiconductor Group Offices in Germany or the Siemens Companies and Representatives worldwide (see address list).

Due to technical requirements components may contain dangerous substances. For information on the types in question please contact your nearest Siemens Office, Semiconductor Group.

Siemens AG is an approved CECC manufacturer.

Packing

Please use the recycling operators known to you. We can also help you - get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Components used in life-support devices or systems must be expressly authorized for such purpose!

Critical components¹ of the Semiconductor Group of Siemens AG, may only be used in life-support devices or systems² with the express written approval of the Semiconductor Group of Siemens AG.

1) A critical component is a component used in a life-support device or system whose failure can reasonably be expected to cause the failure of that life-support device or system, or to affect its safety or effectiveness of that device or system.

2) Life support devices or systems are intended (a) to be implanted in the human body, or (b) to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.